



SOD107A

hermetically sealed plastic package; axial leaded; 2 leads

8 February 2016

Package information

1. Package summary

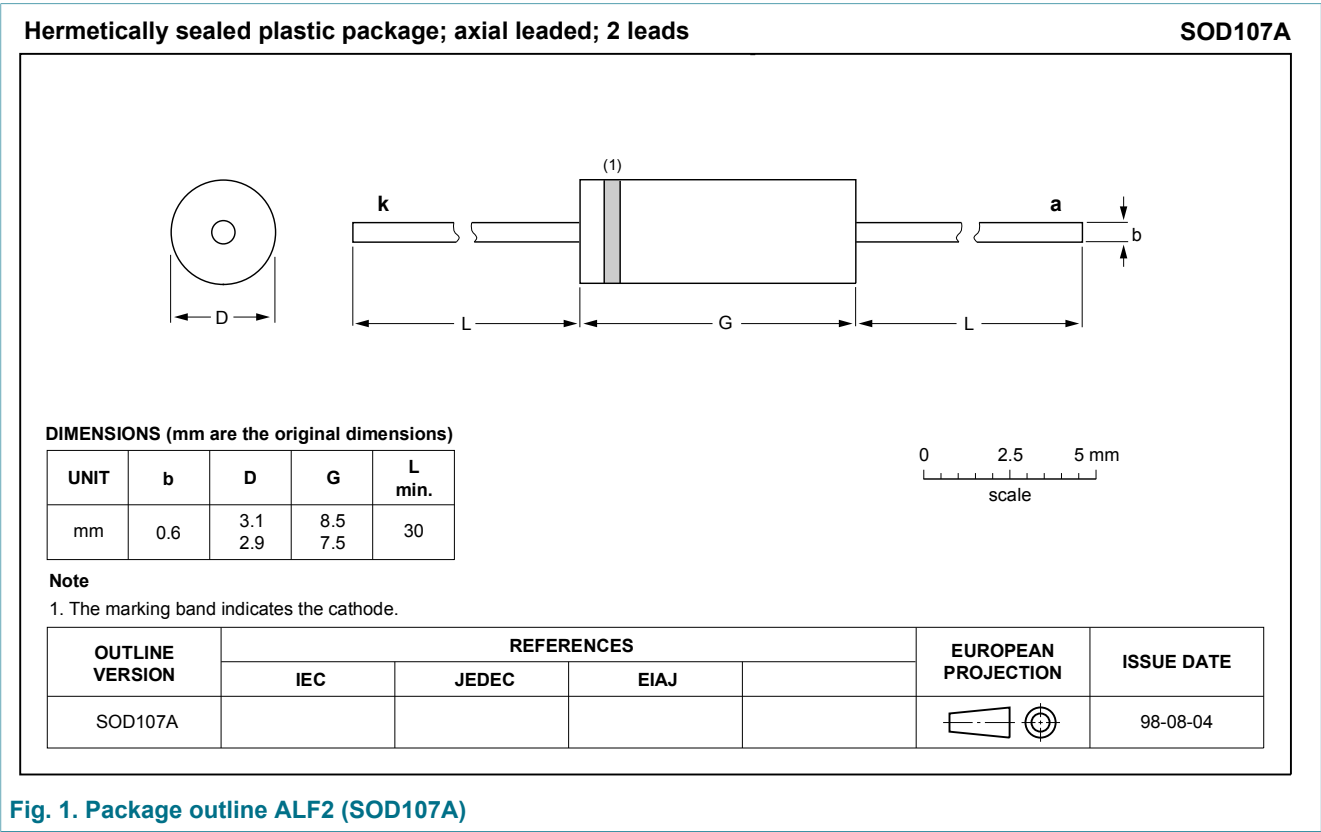
Terminal position code	A (axial)
Package type descriptive code	ALF2
Package type industry code	ALF2
Package style descriptive code	ALF (axial (leaded) long form)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	4-8-1998

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		7.5	-	8	8.5	mm
ΦD	package diameter		2.9	-	3	3.1	mm
n ₂	actual quantity of termination		-	-	2	-	



2. Package outline



3. Legal information

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4. Contents

1. Package summary..... 1

2. Package outline..... 2

3. Legal information..... 3

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